



## Dow Electronic Materials Introduces New Products for Printed Circuit Boards at Productronica Show

### Advanced Technology Improves Performance, Reliability and Environmental Sustainability

**Munich, Germany, November 9, 2009** – [Dow Electronic Materials](#) will introduce its new line of products for printed circuit board (PCB) manufacture at this year's Productronica show (Stand 305, Hall 2, New Munich Trade Fair Center, Germany) on November 10-13. These new products improve performance and reliability, and help meet the electronics industry's requirements for miniaturization, enhanced performance, reduced costs, and reduced environmental impact.

For PCB Imaging, **LAMINAR™ UD-900 Dry Film** photoresist for laser direct imaging has demonstrated capability in a wide range of plating and etching applications. **PHOTOPOSIT™ SN68 Photoresist** is a robust, high-yielding, fine line, cost effective photoresist that can be utilized in manual and automatic exposure equipment at optimum productivity levels. **LITHOJET™ Inkjet Materials** offer print and etch solutions while significantly reducing waste generation; for some customers, use of these materials may result in waste generation reduction of up to approximately 85 percent. **LITHOJET™ 210 Etch Resist** is a new UV-curable acrylic hybrid ink that can dramatically improve yield and quality, as well as reduce manufacturing cost.

For PCB Making Holes Conductive, **CIRCUPOSIT™ 3000-1 Electroless Copper** is a universal plating through hole process capable of low build or high build, basket or rack, and vertical, conveyORIZED vertical or horizontal applications.

For PCB Electrolytic Plating, [MICROFILL™ EVF Copper Via Fill](#) addresses the demand for high density interconnect products using filled microvias: fast filling at low surface copper is achieved. For conventional through hole plating, **COPPER GLEAM™ HT-55 Copper Electroplate** provides exceptional surface distribution and throwing power.

For PCB Final Finish, Dow Electronic Materials continues to invest in the development of new solderable final finishes for the PCB market and extends its product offering with **SILVERON™ MF 100 Autocatalytic Silver**. This new product offers a true multi-functional finish for reflow or wire bond without nickel or thick gold. It also complements our existing electroless nickel immersion gold and electroless nickel electroless palladium immersion gold processes using [DURAPOSIT™ SMT 88 Electroless Nickel](#); [PALLAMERSE™ SMT 2000 Electroless Palladium](#) and [AUROLECTROLESS™ SMT Immersion Gold](#).

"The market drive for miniaturization, enhanced performance, reduced environmental impact and lower costs marches onwards," said Bob Ferguson, global general manager for Dow Electronic Materials. "Dow Electronic Materials is committed to developing technology that improves performance, reliability and sustainability for the PCB industry. Our leading technologies, excellent customer support and extensive global footprint enable us to keep on delivering next generation solutions for the electronic market" he said.



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## About Dow

Dow is a diversified chemical company that combines the power of science and technology with the "Human Element" to constantly improve what is essential to human progress. The Company delivers a broad range of products and services to customers in approximately 160 countries, connecting chemistry and innovation with the principles of sustainability to help provide everything from fresh water, food and pharmaceuticals to paints, packaging and personal care products. In 2008, Dow had annual sales of \$57.4 billion and employed approximately 46,000 people worldwide. The Company has 150 manufacturing sites in 35 countries and produces approximately 3,300 products. On April 1, 2009, Dow acquired Rohm and Haas Company, a global specialty materials company with sales of \$10 billion in 2008, 98 manufacturing sites in 30 countries and approximately 15,000 employees worldwide. References to "Dow" or the "Company" mean The Dow Chemical Company and its consolidated subsidiaries unless otherwise expressly noted. More information about Dow can be found at [www.dow.com](http://www.dow.com).

## About Dow Electronic Materials

Dow Electronic Materials, a global supplier of materials and technologies to the electronics industry, brings innovative leadership to the semiconductor, [interconnect](#), [finishing](#), [photovoltaic](#), display, LED and optics markets. From advanced technology centres worldwide, teams of talented Dow research scientists and application experts work closely with customers, providing solutions, products and technical service necessary for next-generation electronics. These partnerships energize Dow's power to invent. Its key end-use applications include a broad range of consumer electronics from personal computers, to television monitors, cellular phones, global positioning systems, automobile safety systems, and avionics.

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